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To the Honorable Commissioner of

102254207

e attached original documents or copy thereof.

1 Name of conveying party(ies):

Hsing-Kai Huang

10/08/02

2 Name and address of receiving party(ies):

Taiwan Semiconductor Manufacturing Co. Ltd.
No. 121 Park Avenue 3
Science-Based Industrial Park
Hsin-Chu, Taiwan, R.O.C.

3 Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other:

Execution Date: August 12, 2002

Additional name(s) & address(es) attached ☐ Yes ☒ No

4 Application number(s) or patent number(s):

10/266962

If this document is being filed together with a new application, the execution date of the application is: 08-12-02

A. Patent Application No(s).

B. Patent No(s)

Additional numbers attached? ☐ Yes ☒ No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG
Tung & Associates
838 W. Long Lake Road
Suite 120
Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved:

1

7 Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to charge credit card (w/filing fee)

8 Deposit Account Number: 50-0484

(Attach duplicate copy of this page if paying by deposit account)

10/15/2002 MAHRED: 00000009 10266962

02 FC:581

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9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung

Name of Person Signing
Registration No. 31,311

Signature

October 8, 2002

Date

Total number of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231PATENT
REEL: 013384 FRAME: 0492

ASSIGNMENT

WHEREAS, I, HSING-KAI HUANG, have invented certain improvements in

WAFER DRYER SYSTEM FOR PRS WET BENCH

for which I am about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of
No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of
acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and
valuable consideration, the receipt of which is hereby acknowledged, I, HSING-KAI HUANG, by
these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the
territory of the United States of America and all foreign countries, the entire right, title and interest,
including all priority rights under the International Convention associated with each country of the
Union, in and to said invention as described in the patent application executed by me on the 12th
day of August, 2002, preparatory to obtaining Letters Patent of the United States
thereon, and in and to said application and any Letters Patent that may be granted in pursuance of
said application and any divisional, continuation or continuation-in-part application thereof, and in
and to any reissue of any such patent, and in and to any patent applications which may be filed on
said invention in countries foreign to the United States and any Letters Patent granted thereon.

I further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and I further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Hsing-Kai Huang

HSING-KAI HUANG

TUNG & ASSOCIATES
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